

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization

International Bureau



WIPO | PCT



(10) International Publication Number

WO 2017/022236 A1

(43) International Publication Date

9 February 2017 (09.02.2017)

(51) International Patent Classification:

B27N 3/00 (2006.01) C08L 97/02 (2006.01)
C09D 105/00 (2006.01)

(21) International Application Number:

PCT/JP2016/003545

(22) International Filing Date:

2 August 2016 (02.08.2016)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

2015-154777 5 August 2015 (05.08.2015) JP

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, KE, KG, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))



WO 2017/022236 A1

(54) Title: AQUEOUS BONDING COMPOSITION

(57) Abstract: Disclosed is an aqueous bonding composition comprising: (A) a saccharide; (B) a phosphate; and (C) at least one neutralizing agent selected from ammonia and an amine compound having at least one hydroxyl group. The aqueous bonding composition is excellent in balance among bending strength, bending strength under wet condition, water-absorption thickness expansion coefficient and peeling strength and scarcely causes metal to rust. The aqueous bonding composition can be usefully used to produce a wood-based material.

Description

Title of Invention: AQUEOUS BONDING COMPOSITION

Cross-Reference to Related Applications

[0001] This application claims benefit under Paris Convention of Japanese Patent Application No. 2015-154777 filed on August 5, 2015, incorporated herein by reference in its entirety.

Technical Field

[0002] The present invention relates to an aqueous bonding composition capable of producing an aqueous adhesive, and a wood-based material which is producible by using the aqueous bonding composition.

Background Art

[0003] Wood-based materials (for example, plywoods (veneer board, etc.), particle boards, fiber boards (medium density fiber board MDF, etc.), and laminated woods) are generally produced by applying or spraying an adhesive onto a wood-based element (a raw material) (for example, various sizes of fibers, small pieces, and veneers obtained by finely dividing woods or herbaceous plants), followed by molding with optional pressurizing and heating. Wood-based materials are naturally regenerable and are materials in which size and stability of strength are enhanced and thus defects peculiar to woods are removed while utilizing advantages of woods. From the viewpoint of the protection of the earth environment, and the protection of workers of the production of wood-based materials, an aqueous adhesive as the adhesive to be used, which does not cause diffusion of formaldehyde and contains no organic solvent, has been developed.

[0004] When a wood-based material (for example, particle board) is produced using a urea resin and a phenol resin, a mixture of a wood-based element and an adhesive is generally heated to a temperature in a range of about 130 to 170°C and then molded. Therefore, it is preferable that the aqueous adhesive is also heated to approximately the same temperature, thus making it possible to produce the wood-based material. However, when using the aqueous adhesive, higher temperature is often needed.

There is also a need that the wood-based material thus obtained (for example, particle board) is excellent in properties such as bending strength, bending strength under wet condition, water-absorption thickness expansion coefficient, and peeling strength.

However, when using the aqueous adhesive, properties are often unsatisfactory.

[0005] Patent Literature 1 discloses an aqueous solution comprising a starch (wheat flour, etc.) and a saccharide (sucrose, molasses, etc.), and a catalyst (ammonium chloride, zinc chloride, aluminum chloride, ammonium sulfate, ammonium nitrate, diammonium phosphate, etc.) capable of converting them, so as to joint woods (see Examples of

Patent Literature 1).

Patent Literature 1 teaches anhydrous aluminum chloride as a catalyst capable of lowering a heating temperature. The patent document discloses that a particle mat can be obtained at a press temperature of 175°C to 190°C when using aluminum chloride, and that thickness expansion is in a range of about 3 to 10% (see Tables 1 and 2 of Examples of Patent Literature 1). However, aluminum chloride is not suitable since it has corrosiveness to human bodies and vigorously reacts with water to generate hydrogen chloride, leading to emission of irritant odor.

- [0006] Patent Literature 2 discloses an adhesive including a saccharide (sucrose, etc.) and a polycarboxylic acid (citric acid, etc.), so as to joint woods. Inclusion of the polycarboxylic acid leads to an improvement in bonding power with woods. However, the temperature in the case of producing a wood-based material is as high as 200°C. Furthermore, a water-absorption thickness expansion coefficient is as large as about 25% (see Test 2 in Table 10 of Patent Literature 2). The pH decreases because of including the polycarboxylic acid, so that it becomes difficult to store the adhesive. Furthermore, in the case of applying the adhesive using an applicator, metal components of the applicator easily rust.
- [0007] Patent Literature 3 discloses an adhesive including a saccharide (sucrose, maltose, etc.) and a polycarboxylic acid (citric acid, malic acid, maleic anhydride, polymaleic acid, polyacrylic acid, etc.), so as to joint woods. Inclusion of the polycarboxylic acid leads to an improvement in joint power with woods. However, the temperature in the case of producing a wood-based material by molding is as high as 180 to 200°C. The addition of a furan compound enables a decrease in manufacturing temperature and also a decrease in water-absorption thickness expansion coefficient (see Tables 2 to 7 of Patent Literature 3). However, the pH decreases because of including the polycarboxylic acid, so that it becomes difficult to store the adhesive, and metal components of an adhesive applicator easily rust.
- [0008] Therefore, it is required that an aqueous adhesive used to produce a wood-based material is excellent in performances such as water-absorption thickness expansion coefficient while being capable of bonding at a comparatively low temperature, and is also easily stored and does not cause metal components of an applicator to rust.

Citation List

Patent Literature

- [0009] [PTL 1] JP 56-500414 A
- [PTL 2] WO 2010/001988 A1
- [PTL 3] WO 2012/133219 A1

Summary of Invention

Technical Problem

[0010] In light of these circumstances, the present invention has been made and an object thereof is to provide an aqueous bonding composition which is excellent in water-absorption thickness expansion coefficient while being capable of bonding at a comparatively low temperature, and which scarcely causes metal to rust and is particularly useful to produce a wood-based material; and to produce a wood-based material which is obtainable by using the aqueous bonding composition.

Solution to Problem

[0011] As a result of continued intensive study, the present inventors have found that an aqueous bonding composition comprising a saccharide, a phosphate, and a specific neutralizing agent selected from an amine compound having a hydroxyl group and ammonia is excellent in water-absorption thickness expansion coefficient while being capable of bonding at a comparatively low temperature, and which scarcely causes metal to rust and is particularly useful to produce a wood-based material, thus completing the present invention.

[0012] The present invention provides, in an aspect, an aqueous bonding composition comprising: (A) a saccharide; (B) a phosphate; and (C) at least one neutralizing agent selected from ammonia and an amine compound having at least one hydroxyl group.

[0013] The present invention provides, in an embodiment, an aqueous bonding composition, wherein the neutralizing agent (C) has a boiling point of 300°C or lower.

The present invention provides, in another embodiment, an aqueous bonding composition, which has a pH in a range of 6.5 to 10.0.

[0014] The present invention provides, in a further embodiment, an aqueous bonding composition, wherein the saccharide (A) comprises a non-reducing saccharide.

The present invention provides, in another aspect, a wood-based material which is obtainable by using the aqueous bonding composition.

Advantageous Effects of Invention

[0015] The aqueous bonding composition according to the embodiment of the present invention comprises (A) a saccharide, (B) a phosphate, and (C) at least one neutralizing agent selected from ammonia and an amine compound having at least one hydroxyl group, and is therefore excellent in water-absorption thickness expansion coefficient while being capable of bonding at a comparatively low temperature, and scarcely causes metal to rust and is particularly useful to produce a wood-based material.

Description of Embodiments

[0016] The aqueous bonding composition according to the embodiment of the present invention comprises (A) a saccharide, (B) a phosphate, and (C) at least one neu-

tralizing agent selected from ammonia and an amine compound having at least one hydroxyl group.

In the present invention, the “(A) saccharide” is generally called a saccharide and is not particularly limited as long as the objective aqueous bonding composition of the present invention is obtainable. The saccharide (A) includes, for example, monosaccharide, disaccharide, trisaccharide, tetrasaccharide, polysaccharide, and other oligosaccharides.

[0017] Specific examples of the “monosaccharide” include the followings:
hexoses such as glucose, psicose, fructose, sorbose, tagatose, allose, altrose, mannose, gulose, idose, galactose, talose, fucose, fuculose, and rhamnose;
triose such as ketotriose (dihydroxyacetone) and aldotriose (glyceraldehyde);
tetroses such as erythrulose, erythrose, and threose; and
pentoses such as ribulose, xylulose, ribose, arabinose, xylose, lixose, and deoxyribose.

[0018] Examples of the “disaccharide” include sucrose, lactose, maltose, trehalose, turanose, and cellobiose.
Examples of the “trisaccharide” include raffinose, melezitose, and maltotriose.
Examples of the “tetrasaccharide” include acarbose and stachyose.
Examples of the “polysaccharide” include glycogen, starch (amylose, amylopectin, etc.), cellulose, dextrin, glucan, N-acetylglucosamine, chitin, and inulin.
Examples of the “other oligosaccharides” include fructooligosaccharide, galactooligosaccharide, and mannan oligosaccharide.

[0019] These “saccharide(s)” can be used alone or in combination.
The “saccharide” preferably includes a non-reducing saccharide. When the “saccharide” includes the non-reducing saccharide, the aqueous bonding composition of the present invention is more excellent in water resistance, so that the water-absorption thickness expansion coefficient of the wood-based material of the present invention can further decrease.
Examples of the non-reducing saccharide include sucrose, trehalose, maltotriose, inulin, oligosaccharide, and dextrin. When the non-reducing saccharide includes sucrose, the water-absorption thickness expansion coefficient of the wood-based material can further decrease. Inulin usually refers to a polymer of fructose, including glucose linked to the end. Therefore, inulin includes, for example, 1-kestose (GF2) included in simplest trisaccharide, nystose (GF3) included in tetrasaccharide, fructofuranosylnystose (GF4) included in polysaccharide, and the like.
It is possible to use commercially available products as the “saccharide”.

[0020] In the present invention, the “(B) phosphate” is generally called a phosphate and is not particularly limited as long as the objective aqueous bonding composition of the

present invention is obtainable.

Examples of the “phosphate” include a hydrogen phosphate and a dihydrogen phosphate.

Examples of the “phosphate” include phosphonic acid ammonium salts (ammonium phosphate, ammonium hydrogen phosphate, and ammonium dihydrogen phosphate), phosphonic acid sodium salts (sodium phosphate, sodium hydrogen phosphate, and sodium dihydrogen phosphate), phosphonic acid potassium salts (potassium phosphate, potassium hydrogen phosphate, and potassium dihydrogen phosphate), phosphonic acid calcium salts (calcium phosphate, calcium hydrogen phosphate, and calcium dihydrogen phosphate), phosphonic acid magnesium salts (magnesium phosphate, magnesium hydrogen phosphate, and magnesium dihydrogen phosphate), and the like.

[0021] The “phosphate” is preferably at least one selected from ammonium phosphates (ammonium phosphate, ammonium hydrogen phosphate, and ammonium dihydrogen phosphate).

When the “(B) phosphate” is at least one selected from ammonium phosphates (ammonium phosphate, ammonium hydrogen phosphate, and ammonium dihydrogen phosphate), the aqueous bonding composition of the present invention is excellent in curability.

The “(B) phosphate(s)” can be used alone or in combination.

It is possible to use commercially available products as the “(B) phosphate”.

[0022] In the present invention, the “(C) neutralizing agent” includes at least one selected from ammonia and an amine compound having at least one hydroxyl group.

The “amine compound having at least one hydroxyl group” refers to an amine compound having one or more hydroxyl groups and is not particularly limited as long as the objective aqueous bonding composition of the present invention is obtainable.

The “ammonia” generally refers to a compound which is generally called ammonia, and may be in the form of an aqueous solution prepared by being dissolved in water (usually called ammonia water), and is not particularly limited as long as the objective aqueous bonding composition of the present invention is obtainable.

[0023] Examples of the “(C) neutralizing agent” include ammonia, 2-amino-2-methylpropanol, diethanolamine, N,N-dimethylaminoethanol, and triethanolamine, and is more preferably:

at least one selected from ammonia, 2-amino-2-methylpropanol, diethanolamine, and N,N-dimethylaminoethanol.

[0024] When the neutralizing agent (C) is at least one selected from ammonia, 2-amino-2-methylpropanol, diethanolamine, and N,N-dimethylaminoethanol, the water-absorption thickness expansion coefficient of the wood-based material can decrease.

[0025] The neutralizing agent (C) preferably has a boiling point of 300°C or lower, and more preferably in a range of -40°C to 280°C. If the neutralizing agent has a boiling point of 300°C or lower, when using the aqueous bonding composition of the present invention, metal components of an adhesive applicator more scarcely rust, and thus the water-absorption thickness expansion coefficient of the wood-based material can further decrease.

The neutralizing agent(s) (C) can be used alone or in combination.

It is possible to use commercially available products as the neutralizing agent (C).

[0026] The component (A) is preferably included in an amount of 20 to 95 parts by weight, more preferably 50 to 90 parts by weight, and particularly preferably 60 to 85 parts by weight, based on 100 parts by weight of the total amount of the components (A) to (C).

The component (B) is preferably included in an amount of 1 to 50 parts by weight, more preferably 3 to 35 parts by weight, and particularly preferably 5 to 25 parts by weight, based on 100 parts by weight of the total amount of the components (A) to (C).

The component (C) is preferably included in an amount of 0.5 to 50 parts by weight, more preferably 1 to 35 parts by weight, and particularly preferably 2 to 25 parts by weight, based on 100 parts by weight of the total amount of the components (A) to (C).

[0027] If the component (A) is included in an amount of 20 to 95 parts by weight, the water-absorption thickness expansion coefficient of the wood-based material of the present invention can further decrease.

If the component (B) is included in an amount of 1 to 50 parts by weight, the aqueous bonding composition of the present invention can have more excellent curability.

If the component (C) is included in an amount of 0.5 to 50 parts by weight, when using the aqueous bonding composition of the present invention, metal components of an adhesive applicator may more scarcely rust, and thus the water-absorption thickness expansion coefficient of the wood-based material can further decrease.

[0028] The aqueous bonding composition according to the present invention includes water, and has a form of an aqueous solution in which all of the above-mentioned components (A) to (C) are dissolved in water, or a form of a dispersion in which at least one of the above-mentioned components (A) to (C) is dispersed without being dissolved in water.

The “water” as used herein is generally called “water” and is not particularly limited as long as the objective aqueous bonding composition of the present invention is obtainable. Examples thereof can include distilled water, deionized water, pure water, tap water, and industrial water.

The amount of water contained in the aqueous bonding composition according to the embodiment of the present invention is not particularly limited as long as the objective aqueous bonding composition of the present invention is obtainable, and is appropriately selected considering the components (A) to (C) to be used and additives.

[0029] The aqueous bonding composition according to the embodiments of the present invention preferably includes water in an amount of 10 to 90 parts by weight, more preferably 20 to 80 parts by weight, and particularly preferably 30 to 60 parts by weight, based on 100 parts by weight of the total amount of the components (A) to (C).

The aqueous bonding composition according to the present invention is in a form of an aqueous solution or a water dispersion, so that it is easy to apply or spray onto an adherend. Furthermore, the aqueous bonding composition according to the present invention is excellent in protection of the earth environment, and protection of the work environment of workers because an organic solvent is not preferably used.

[0030] The aqueous bonding composition according to the embodiments of the present invention can include other components. Examples of the component can include a thickener, a preservative, a mildew-proofing agent, a rust preventive, a dispersion stabilizer and so on.

The thickener is used to prevent a viscosity of the composition from decreasing in the case of pressurizing and heating, and is not particularly limited as long as the objective aqueous bonding composition of the present invention is obtainable. The thickener is classified, for example, into an organic thickener and an inorganic thickener.

Examples of the inorganic thickener can include clay, talc, silica and so on.

Examples of the organic thickener can include carboxymethyl cellulose, polyvinyl alcohol, and vegetable flours such as wheat flour, cornstarch, top-grade rice flour, walnut flour, coconut flour, and so on.

These thickeners can be used alone or in combination.

[0031] The pH of the aqueous bonding composition according to an embodiment of the present invention is preferably in a range of 6.5 to 10.0, more preferably 7.5 to 9.5, and particularly preferably 7.0 to 9.0.

The pH of the aqueous bonding composition is more preferably in a range of 6.5 to 10.0, since the composition can be stored easier and scarcely cause metal components of an applicator to rust.

[0032] The aqueous bonding composition according to the embodiment of the present invention can be produced by mixing the above-mentioned components (A) to (C), optional other components and water, followed by stirring. The order of mixing, the mixing method, and the stirring method are not particularly limited as long as the objective aqueous bonding composition of the present invention is obtainable.

[0033] The wood-based material according to the present invention is produced by applying or spraying the aqueous bonding composition according to the embodiments of the present invention onto a wood-based element (raw material) (for example, small pieces, veneers, fibers of wood-based or herbaceous plants, etc.), heating and pressurizing the wood-based element to cure the aqueous bonding composition, leading to

bonding of the wood-based element, followed by molding.

Examples of the wood-based element (raw material) include, for example, sawn boards, veneers, wood-based strands, wood-based chips, wood-based fibers and vegetable fibers, and the like obtainable, for example, by grinding woods etc.,. These wood-based elements can be used alone or in combination.

Examples of the wood-based material include, for example, laminated woods, plywoods, particle boards, fiber boards, MDF, and the like obtainable, for example, by bonding the wood-based element using an adhesive.

The aqueous bonding composition according to the embodiments of the present invention can be used to bond various adherends (for example, papers, wood-based fibers, plywoods, etc.), and can be suitably used to produce the wood-based material.

[0034] In the case of producing the wood-based material by molding, manufacturing condition such as coating amount of the aqueous bonding composition, coating method, molding pressure, molding temperature, and molding time are appropriately selected according to the type, shape and size of the wood-based element, and the size of the wood-based material to be produced, and are not particularly limited as long as the objective wood-based material of the present invention is obtainable.

The coating amount of the aqueous bonding composition is preferably in a range of 5 to 80 parts by weight, more preferably 10 to 60 parts by weight, and particularly preferably 20 to 40 parts by weight, based on 100 parts by weight of a dried wood-based element.

[0035] The coating method of the aqueous bonding composition is preferably a coating method using a roll and a brush, a spraying method using a spray, a method of impregnating with the aqueous bonding composition, or the like.

The molding pressure is preferably in a range of 0.5 to 6.0 MPa. If the molding pressure is 6.0 MPa or less, the wood-based material is scarcely degraded since too large pressure is not applied. If the molding pressure is 0.5 MPa or more, it is possible to satisfactorily bond the wood-based element.

[0036] The molding temperature is preferably in a range of 150 to 230°C, more preferably 155 to 200°C, and particularly preferably 160 to 180°C. If the molding temperature is 230°C or lower, the temperature is not too high, energy consumption is low, and also the wood-based material is scarcely degraded. If the molding is carried out at a temperature of 150°C or higher, the bonding can proceed within an appropriate time.

[0037] The molding time is preferably in a range of 5 to 10 minutes, more preferably 6 to 9 minutes, and particularly preferably 7 to 8 minute. If the molding time is 10 minutes or less, low energy consumption is achieved because of non-excessive time, and also the wood-based material is scarcely degraded. If the molding time is 5 minutes or more, an appropriate bonding time is secured, thus making it possible to secure appropriate

bonding.

[0038] The wood-based material thus obtained in the above-mentioned manner can be used for various applications, for example, building materials and furniture etc., like conventional wood-based materials.

Examples

[0039] The present invention will be described below by way of Examples and Comparative Examples. It should be noted, however, these Examples are intended to describe the present invention and the present invention is not limited thereto.

[0040] First, the following components were prepared as components of an aqueous bonding composition. Trade name and manufacturer's name are shown in parentheses. Parts are by weight.

<(A) Saccharide>

(A-1) Sucrose (Wako Pure Chemical Industries, Ltd.)

[0041] <(B) Inorganic Acid Ammonium Salt>

(B-1) Ammonium dihydrogen phosphate (Wako Pure Chemical Industries, Ltd.)

<(C) Neutralizing Agent>

(C-1) Ammonia (25% ammonia water, Wako Pure Chemical Industries, Ltd.)

(C-2) 2-Amino-2-methylpropanol (Wako Pure Chemical Industries, Ltd.)

(C-3) Diethanolamine (Wako Pure Chemical Industries, Ltd.)

(C-4) Triethanolamine (Wako Pure Chemical Industries, Ltd.)

(C'-5) Sodium hydroxide (Wako Pure Chemical Industries, Ltd.)

[0042] An aqueous bonding composition of Example 1 was produced in the following manner.

<Example 1: Production of aqueous bonding composition>

78.0 Parts of (A-1) sucrose (Wako Pure Chemical Industries, Ltd.) and 19.5 parts of (B-1) ammonium dihydrogen phosphate (Wako Pure Chemical Industries, Ltd.) were dissolved in 92.5 parts of distilled water. To this aqueous solution, 2.5 parts of (C-1) ammonia (containing 2.5 parts of ammonia and 7.5 parts of water because of using 10.0 parts of 25% ammonia water, Wako Pure Chemical Industries, Ltd.) was added. After stirring at normal temperature, an aqueous bonding composition of Example 1 was obtained. The composition of the aqueous bonding composition of Example 1 is shown in Table 1.

[0043] <Measurement of pH>

The pH of the aqueous composition of Example 1 was measured at 23°C using a pH meter (Model HM-25R (trade name) manufactured by DKK-TOA CORPORATION). As a result, the pH was 7.0. The results are shown in Table 1.

[0044] <Rust Test>

The aqueous bonding composition (40 g) of Example 1 was charged in a 100 mL glass container with a lid. A commercially available iron nail having a length of 70 mm degreased with isopropanol was put in the aqueous adhesive composition. After being left to stand at 23°C for 7 days, generation of rust was observed.

- A: Rust was not generated for 7 days.
- B: Rust was generated within 3 to 7 days.
- C: Rust was generated within 1 to 3 days.
- D: Rust was generated within 1 day.

[0045] <Examples 2 to 6 and Comparative Examples 7 to 10: Production of aqueous bonding compositions>

The composition of each of aqueous bonding compositions of Examples 2 to 6 and Comparative Examples 7 to 10 is shown in Tables 1 to 2.

In the same manner as in Example 1, except that the components (A), (B), and (C) used in Example 1 were changed to components shown in Tables 1 to 2 and amounts thereof, the aqueous bonding compositions of Examples 2 to 6 and Comparative Examples 7 to 10 were produced.

In the same manner as in Example 1, the pH was measured and also the rust test was performed. The results are shown in Tables 1 to 2.

[0046] [Table 1]

Composition (Examples)	1	2	3	4	5	6
(A) (A-1)	78.0	77.4	75.5	68.6	66.6	60.9
(B) (B-1)	19.5	19.3	18.9	17.2	16.7	15.2
(C) (C-1)	2.5	3.3	5.6			
(C-2)				13.9		
(C-3)					16.7	
(C-4)						23.8
(C'-5)						
Water	100	100	100	100	100	100
pH	7.0	9.0	9.9	8.3	8.4	8.1
Rust test	B	A	A	A	A	A

[0047]

[Table 2]

Composition	(Comparative Example)	7	8	9	10
(A)	(A-1)	74.3	100		80.0
(B)	(B-1)	18.6		100	20.0
(C)	(C-1)				
	(C-2)				
	(C-3)				
	(C-4)				
	(C'-5)	7.1			
Water		100	100	500	100
	pH	8.5	6.8	3.3	3.3
	Rust test	A	B	D	D

[0048] Using the above-mentioned aqueous bonding compositions of Examples 1 to 6 and Comparative Examples 7 to 10, wood-based materials (particle boards) of Examples 11 to 16 and Comparative Examples 17 to 20 were produced.

<Example 11: Production of wood-based material>

Wood-based fibers of coniferous tree, which passed through a 60 mesh sieve, were used as a wood-based element (raw material). The aqueous adhesive composition of Example 1 was uniformly applied onto 76 parts of the wood-based element using a spray so that the solid content became 24 parts. The coated wood-based element was dried in an oven at 80°C for 2 hours. After press molding at a heating platen temperature of 170°C under a pressure of 4 MPa for 9 minutes, a wood-based material (particle board) having a thickness of 9 mm and a density of 0.8 g/cm³ of Example 11 was produced. The raw materials and manufacturing conditions of the wood-based material of Example 11 are shown in Table 3.

[0049] <Examples 12 to 16 and Comparative Examples 17 to 20: Production of wood-based materials>

Raw materials used to produce particle boards of Examples 12 to 16 and Comparative Examples 17 to 20, amounts thereof, and press molding conditions are shown in Tables 3 to 4.

In the same manner as in Example 11, except that the aqueous adhesive composition used in Example 11, the amount thereof, the amount of the wood-based element, and the press molding conditions (heating platen temperature, pressure, and molding time) were changed to the values shown in Tables 3 to 4, wood-based materials (particle boards) of Examples 12 to 16 and Comparative Examples 17 to 20 were produced. Other conditions such as size and density of each particle board are the same as those of the particle board of Example 11.

[0050] Regarding the particle board thus obtained, each water-absorption thickness expansion coefficient (%) was measured in accordance with JIS A5908:2003.

The “water-absorption thickness expansion coefficient (%)” is preferably 12 or less. The above-mentioned particle board corresponds to a “non-polished board” of a “base particle board” disclosed in JISA5908:2003.

[0051] [Table 3]

Wood-based material (Example)		11	12	13	14	15	16
Composition	Wood-based element	Parts by weight	76	76	76	76	76
	Bonding composition	(Example)	1	2	3	4	5
		Parts by weight	24	24	24	24	24
Molding conditions	Temperature	°C	170	170	170	170	170
	Time	Minutes	9	9	9	9	9
	Pressure	MPa	4	4	4	4	4
Performances	Water-absorption thickness expansion coefficient (%)		12.0	11.3	11.2	11.9	10.5
							14.8

[0052] [Table 4]

Wood-based material (Comparative Example)		17	18	19	20
Composition	Wood-based element	Parts by weight	76	72	94
	Bonding composition	(Comparative Example)	7	8	9
		Parts by weight	24	28	6
Molding conditions	Temperature	°C	170	170	170
	Time	Minutes	9	9	9
	Pressure	MPa	4	4	4
Performances	Water-absorption thickness expansion coefficient (%)		Collapse	Collapse	Collapse
					20.4

*Collapse: The wood-based material was broken so that it became difficult to maintain the whole form during the evaluation.

[0053] As shown in Tables 3 and 4, each of the wood-based materials of Examples 11 to 16, produced using the aqueous bonding compositions of Examples 1 to 6, has a small water-absorption thickness expansion coefficient. Furthermore, each of the aqueous bonding compositions of Examples 1 to 6 can prevent the nail from rusting. Therefore, the bonding compositions according to the present invention can be suitably used (or applied) to a wood-based element so as to produce a wood-based material.

As shown in Table 4, the wood-based materials of Comparative Examples 17 to 20 produced by using the aqueous bonding compositions of Comparative Examples 7 to 10 are inferior in water-absorption thickness expansion coefficient. Furthermore, the aqueous bonding compositions of Comparative Examples 9 and 10 cannot prevent the nail from rusting because of the low pH.

[0054] These results revealed that the aqueous bonding composition comprising the above-mentioned three components (A) to (C) is useful for bonding a wood-based element (raw material) and an excellent wood-based material can be molded by molding a wood-based element using the same.

Industrial Applicability

[0055] The present invention can provide an aqueous bonding composition which is useful for bonding a wood-based element. A wood-based material can be suitably produced by molding a wood-based element using the aqueous bonding composition according to the present invention.

Claims

[Claim 1] An aqueous bonding composition comprising: (A) a saccharide; (B) a phosphate; and (C) at least one neutralizing agent selected from ammonia and an amine compound having at least one hydroxyl group.

[Claim 2] The aqueous bonding composition according to claim 1, wherein the neutralizing agent (C) has a boiling point of 300°C or lower.

[Claim 3] The aqueous bonding composition according to claim 1 or 2, which has a pH in a range of 6.5 to 10.0.

[Claim 4] The aqueous bonding composition according to any one of claims 1 to 3, wherein the saccharide (A) includes a non-reducing saccharide.

[Claim 5] A wood-based material coated with the aqueous bonding composition according to any one of claims 1 to 4.

INTERNATIONAL SEARCH REPORT

International application No
PCT/JP2016/003545

A. CLASSIFICATION OF SUBJECT MATTER
INV. B27N3/00 C09D105/00 C08L97/02
ADD.

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)
B27N C09D C08L

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

EPO-Internal, BIOSIS, COMPENDEX, WPI Data

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	WO 2009/010393 A1 (CIBA HOLDING INC [CH]; CAMPBELL JONATHAN [CH]; KAESER ADOLF [CH]; HOEK) 22 January 2009 (2009-01-22) page 20, line 1 - page 22, line 3 ----- US 2007/027283 A1 (SWIFT BRIAN L [US] ET AL) 1 February 2007 (2007-02-01) paragraph [0038]; table 5 ----- US 6 982 049 B1 (MABEY MICHAEL JOHN [CA] ET AL) 3 January 2006 (2006-01-03) claims; examples 1-5 ----- GB 2 451 719 A (KNAUF INSULATION LTD [GB]) 11 February 2009 (2009-02-11) page 10 -----	1-4 1,2 1-3,5 1-3,5



Further documents are listed in the continuation of Box C.



See patent family annex.

* Special categories of cited documents :

- "A" document defining the general state of the art which is not considered to be of particular relevance
- "E" earlier application or patent but published on or after the international filing date
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- "O" document referring to an oral disclosure, use, exhibition or other means
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"Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art

"&" document member of the same patent family

Date of the actual completion of the international search

Date of mailing of the international search report

17 October 2016

26/10/2016

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INTERNATIONAL SEARCH REPORT

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